

LM12458

AN-947 Interfacing the LM12458 Data Acquisition System to the MC68HC11AX

Microcontroller



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Interfacing the LM12458 Data Acquisition System to the MC68HC11AX Microcontroller

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1.0 INTRODUCTION

This application note shows how to interface Motorola's MC68HC11 family of microcontrollers to the LM12458 parallel data acquisition system (DAS). It is intended to give the reader a better understanding of the DAS and how it can be integrated in a $\mu P/\mu C$ system. There is a brief description of the MC68HC11Ax and the LM12458. An example is provided that will illustrate how to use the DAS in a system where a specific sampling rate is desired, single-ended and differential measurements of multiple channels need to be made, and alarm conditions must be monitored. The application note provides a detailed circuit schematic showing the interface circuitry of the DAS to the 68HC11 accompanied with the appropriate assembly code necessary to program the DAS to fulfill the specific requirements of the example.

2.0 GENERAL OVERVIEW OF THE MC68HC11AX AND THE LM12458 DAS

2.1 MC68HC11Ax

The 68HC11 is an 8-bit microcontroller with a 16-bit address range. It has two user modes of operation: single-chip and expanded-multiplexed mode. In single-chip mode, the 68HC11 has no external data bus or address bus. It communicates with external peripherals using its I/O ports. In expanded-multiplexed mode, the 68HC11 uses its 8-bit I/O ports B and C as address and data buses. Port B is the upper address byte. The lower address byte and the data bus are multiplexed together on port C. An address strobe (AS) generated by the 68HC11 indicates when the lower address byte is on port C. This signal may be used with external latches to demultiplex the lower address byte and data bus. In a read or write cycle the address is first placed on ports B and C and the AS is asserted. After a certain time period has elapsed, data is placed on port C. Refer to the manual of the 68HC11 for detailed timing diagrams. The 68HC11 has a R/\overline{W} control signal that indicates the direction of data flow with respect to the μC . This signal in conjunction with the E clock may be used to generate read (\overline{RD}) and write (\overline{WR}) signals going to the DAS and other peripherals. The 68HC11 has two 8-bit accumulators, ACCA and ACCB and a 16-bit accumulator ACCD that are used for manipulating data. ACCD is a cascade of ACCA and ACCB. When using ACCD to read from or write to memory, data is not transferred in a single 16-bit word but a succession of two 8-bit bytes. Data is first transferred via ACCA, followed by ACCB. *Figure 1* shows a block diagram of the MC68HC11Ax in expanded multiplexed mode.

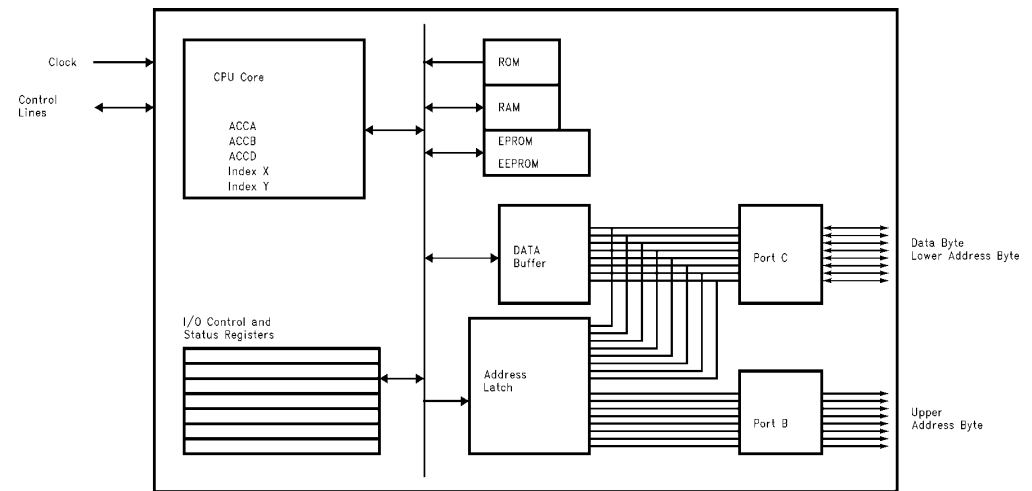


FIGURE 1. Block Diagram of the MC68HC11Ax in Expanded Multiplexed Mode

TL/H/12050-1

2.2 LM12458 DAS

The LM12458 is a 12-bit + sign parallel ADC that has an Instruction RAM, Configuration register, FIFO, Timer register, Interrupt Enable and Status register, watchdog detection circuitry, and an eight channel fully differential multiplexer. The DAS has three modes of operation: 12-bit + sign conversion, 8-bit + sign conversion and an 8-bit watchdog comparison mode.

The Instruction RAM has eight 48-bit wide programmable instruction registers (INSTR0–INSTR7). These instructions are used to set the mode of the DAS, the acquisition time, channels that are to be converted and the watchdog limits. The watchdog detects when a particular channel has passed a programmed limit set in the Instruction RAM. Refer to section 2.1 of the data sheet for a detailed description of the Instruction RAM and the watchdog feature. The MUX channel assignments are also set in the Instruction RAM. Table I in section 2.3 of the data sheet gives the MUX address channel assignments. The Configuration register is the control “panel” of the DAS. Its bits start/stop instruction execution, reset the DAS, perform a full calibration and

auto-zero. Refer to section 2.2 of the data sheet for a detailed description of the configuration register. The FIFO has thirty-two 16-bit wide locations. The FIFO stores the conversion data performed by the ADC. Refer to section 3.0 of the data sheet for a detailed description of the FIFO. The DAS has an internal Timer used to delay execution of an instruction by a related amount of clock cycles programmed in the Timer register. Refer to section 2.7 of the data sheet for a detailed description of the timer. The Interrupt Enable register can set up eight different sources that will cause interrupts to occur and the Interrupt Status register indicates the sources of these interrupts. Refer to section 2.4 of the data sheet for a detailed description of the Interrupt Enable register and the Interrupt Status register.

3.0 SYSTEM EXAMPLE

3.1 Furnace Description and System Requirements

A high temperature semiconductor furnace will be the source of the analog signals going to the inputs of the DAS. Refer to *Figure 2* for a detailed setup of the furnace and the signals from the furnace that need to be digitized.

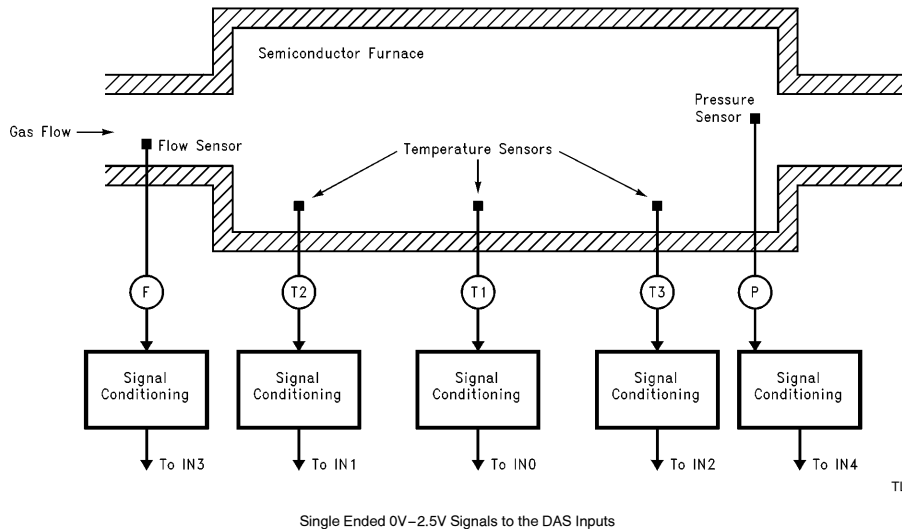


FIGURE 2. Signal Measurement Arrangements of the Semiconductor Furnace

The DAS will measure:

- T1 at IN0 with 12-bit resolution. (single-ended)
- T1–T2 with 12-bit + sign resolution. T2 is connected to IN1. (differential)
- T1–T3 with 12-bit + sign resolution. T3 is connected to IN2. (differential)
- The gas flow, F at IN3 with 8-bit resolution and an extended acquisition. (single-ended)
- The pressure, P at IN4 with 8-bit resolution. (single-ended)

The DAS will also be used to monitor three alarm conditions.

- Gas flow, F exceeds a maximum limit.
- Gas flow, F falls below a minimum limit.
- Pressure, P exceeds a maximum limit.

The following assumptions are made about the furnace system:

- All the analog signals to be measured by the DAS are conditioned so that their voltage levels are within the range 0V–2.5V.
- The output of the flow sensor signal conditioning circuit has a 600Ω source impedance.
- The DAS reference voltage is 2.5V. ($V_{REF+} = 2.5V$ and $V_{REF-} = AGND$)
- The DAS is to achieve a throughput rate of 50 Hz per signal measured.

The DAS will be programmed as follows:

- Seven instructions, INSTR0 through INSTR6 of the Instruction RAM will be used.

INSTR0: Watchdog mode for the gas flow, F, with the acquisition factor $D = 1$. The timer bit is also set.

INSTR1: Watchdog mode for the gas pressure P.

INSTR2: Measure T1 at IN0 with 12-bit resolution. $V_{IN+} = IN0$ and $V_{IN-} = AGND$.

INSTR3: Measure T1–T2 with 12-bit + sign resolution. T2 is connected to IN1. $V_{IN+} = IN0$ and $V_{IN-} = IN1$.

INSTR4: Measure T1–T3 with 12-bit + sign resolution. T3 is connected to IN2. $V_{IN+} = IN0$ and $V_{IN-} = IN2$.

INSTR5: Measure the gas flow, F at IN3 with 8-bit resolution and the acquisition factor $D = 1$. $V_{IN+} = IN3$ and $V_{IN-} = AGND$.

INSTR6: Measure the pressure, P at IN4 with 8-bit resolution. $V_{IN+} = IN4$ and $V_{IN-} = AGND$.

- The DAS loops back to INSTR0 after executing INSTR6. Each loop is called an instruction loop.
- Each instruction loop generates five conversion results. The DAS is programmed to interrupt the 68HC11 when the FIFO has five conversions stored in it. This interrupt will occur after execution of INSTR6 in every instruction loop at which time the FIFO will be read by the 68HC11.
- The DAS will not be stopped when the FIFO is read. The FIFO is read during the time delay added between INSTR6 and INSTR0.

Since the flow sensor circuitry has an output impedance of 600Ω, it requires additional acquisition time. From the data sheet, the acquisition factor D in 8-bit mode is:

$$D = 0.36 * R_S * f_{CLK}$$

$$D = 0.36 * 0.600 * 5 = 1.08$$

$$D = 1$$

3.2 DAS Registers

The following registers contain the necessary values to satisfy the system requirements.

Instruction Register Definition for RP = 00

D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
Acquisition Time				W-dog	8/12	Timer	Sync	V_{IN-}			V_{IN+}			Pause	Loop

INSTR0: Watchdog Mode for Flow, D = 1, Timer Enabled

$V_{IN+} = IN3, V_{IN-} = AGND$

D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
0	0	0	1	1	0	1	0	0	0	0	0	1	1	0	0

INSTR1: Watchdog Mode for Pressure

$V_{IN+} = IN4, V_{IN-} = AGND$

D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
0	0	0	0	1	0	0	0	0	0	0	1	0	0	0	0

INSTR2: Measuring T1, Single-Ended, 12-Bit

$V_{IN+} = IN0 (T1), V_{IN-} = AGND$

D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

INSTR3: Measuring T1-T2, Differential, 12-Bit + Sign

$V_{IN+} = IN0 (T1), V_{IN-} = IN1 (T2)$

D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0

INSTR4: Measuring T1-T3, Single-Ended, 12-Bit + Sign

$V_{IN+} = IN0 (T1), V_{IN-} = IN2 (T3)$

D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0

INSTR5: Measuring Flow, Single-Ended, 8-Bit, D = 1

$V_{IN+} = IN3, V_{IN-} = AGND$

D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
0	0	0	1	0	1	0	0	0	0	0	0	1	1	0	0

INSTR6: Measuring Pressure, Single-Ended, 8-Bit, Loop Bit Set

$V_{IN+} = IN4, V_{IN-} = AGND$

D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
0	0	0	0	0	1	0	0	0	0	0	1	0	0	0	1

3.2 DAS Registers (Continued)

Instruction RAM, Limits Definition

D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
Don't Care						>/<	Sign	Limit							

INSTR0, Limit # 1, RP = 01

D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
0	0	0	0	0	0	1	0	Flow_Max							

INSTR0, Limit # 2, RP = 10

D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
0	0	0	0	0	0	0	0	Flow_Min							

INSTR1, Limit # 1, RP = 01

D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
0	0	0	0	0	0	1	0	Pres_Max							

INSTR1, Limit # 2, RP = 10

D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
0	0	0	0	0	0	0	0	Pres_Min							

Interrupt Enable Register Definition

D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
Number of Results in FIFO					Instruction Number			INT7	INT6	INT5	INT4	INT3	INT2	INT1	INT0

Watchdog Limit, FIFO Full (Conv = 5), and Auto-Zero Interrupts Enabled

D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
0	0	1	0	1	0	0	0	0	0	0	1	0	1	0	1

Configuration Register Definition

D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
Don't Care			Diag	Test	RAM Pointer	Sync I/O	A/Z Each	Chan Mask	Standby	Full Cal	Auto Zero	Reset	Start		

Configuration Register Start Command with SYNC Out

D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	1

Configuration Register Reset Command

D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0

Configuration Register Full Calibration Command

D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
0	0	0	0	0	0	0	0	0	0	0	0	1	0	0	0

3.3 Determining the Throughput Rate

The following table gives the number of clock cycles each instruction takes to execute. The total number of clock cycles may then be used to determine how long it will take for all the instructions to be executed. This will aid in calculating the throughput rate of the DAS.

Instruction Number	State 0	State 1	State 7	State 6	State 4	State 5	Clock Cycles
0	1	1	9			44	55
1	1	1	9			44	55
2	1	1	9			44	55
3	1	1	6			21	29
4	1	1	2			21	25
5	1	1	6	5	1	5	19
6	1	1	2	5	1	5	15
Total							253

Since the timer will be used, an additional 2 clock cycles need to be added to the total 253.

The total time it takes to execute a full instruction loop with a clock frequency (f_{CLK}) of 5 MHz is:

$$(253 + 2) * 200 \text{ ns} = 51 \mu\text{s}$$

In addition to the instruction loop execution time, there is some delay time added at the end of the instruction loop for each chip select made to the DAS when reading the five conversions stored in the FIFO. Whenever chip select is asserted, all clock dependent activities of the DAS come to a halt. This delay is the total amount of time that chip select has gone low when reading the FIFO. Each chip select cycle is 500 ns long (refer to the timing diagrams). There are five conversions, two bytes each, that will be read. This gives a total of ten chip selects (one chip select per byte). Ten chip selects at 500 ns per chip select gives a total delay time of 5 μs , so the time required to complete an instruction loop and read the conversion results is 51 μs + 5 μs = 56 μs . The desired throughput rate is 50 Hz (a sample per channel every 20 ms). This implies that a delay time between instruction loops must be added. The delay time is equal to:

$$20 \text{ ms} - 56 \mu\text{s} = 19.944 \text{ ms}$$

This time delay may be inserted between instruction loops by setting the timer bit in INSTR0. The amount of the time delay is related to the value stored in the timer register. The following shows how to calculate the value to put in the timer register to give a delay of 19.944 ms:

The number of 5 MHz clock cycles in 19.944 ms is:
 $19.944 \text{ ms} * 5 \text{ MHz} = 99720 \text{ clock cycles}$

The timer increments every 2^5 (32) clock cycles. Therefore, the value to be placed in the timer register is:
 $99720/32 = (3116.25)_{\text{base}10}$
 $= (\mathbf{0C2C})_{\text{base}16}$

The 0.25 fraction is lost when converting $(3116.25)_{\text{base}10}$ to hexadecimal. This results in decreasing the delay time by eight 5 MHz clock cycles ($8 * 200 \text{ ns} = 1.6 \mu\text{s}$) to 19.9424 ms. So the actual throughput rate is:

$$19.9424 \text{ ms} + 56 \mu\text{s} = 19.9984 \text{ ms}$$

$$\frac{1}{19.9984 \text{ ms}} = \mathbf{50.004 \text{ Hz}}$$

4.0 SYSTEM OVERVIEW

4.1 How to Communicate with the DAS

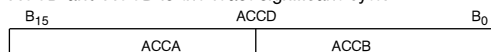
In developing the software and circuitry to program the DAS for the furnace example, Motorola's EVM development system for emulating the MC68HC11A8 was used. In this application note it is assumed that the reader is already familiar with the architecture and instruction set of the MC68HC11A8. The reader should also be familiar with the LM12(H)454/8 DAS by having previously read the data sheet. In this design the μC 's E_{clock} is 2 MHz and the DAS clock is running at 5 MHz.

The DAS can be selected to run on an 8-bit or a 16-bit data bus. Since we are using an 8-bit μC the DAS must be configured to operate in 8-bit mode. This is done by hardwiring the "BW" pin to a logic 1. The internal registers of the DAS are all 16 bits long, so in order to read from and write to a 16-bit register while in 8-bit mode, data transfer must take place in two cycles. In fact when in 8-bit mode the internal registers are byte addressable. The 68HC11 architecture and instruction set facilitates this transfer of data in two ways. One way is using standard 8-bit reads and writes via the 8-bit accumulators. For example, a 16-bit write to the configuration register:

```
LDAA #DATA1 ;DATA1 is the least significant
;byte (LSB).
STAA CONFIG1 ;CONFIG1 = Address of LSB of
;the configuration register.
LDAA #DATA2 ;DATA2 is the most significant
;byte (MSB).
STAA CONFIG2 ;CONFIG2 = Address of MSB of
;the configuration register.
```

Notice that it takes 4 instructions to do this.

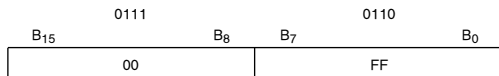
Another way of achieving the same results with half the number of instructions is to use the 68HC11's 16-bit double accumulator D. This accumulator is an actual cascading of ACCA and ACCB. ACCA is the most significant byte of ACCD and ACCB is the least significant byte.



When using ACCD the instruction set emulates that of a 16-bit processor. The above example becomes:

```
LDD #DATA ;DATA is 16 bits.
STD CONFIG ;Address of configuration
;register.
```

This is not a true single 16-bit transfer of data but a succession of 8-bit ones. When using ACCD the user should notice that data is first transferred from ACCA followed by data from ACCB. This plays an important role in determining the data that is sent to and received from the DAS. To demonstrate this let's look at an example that will write #00FFh to the configuration register located at address 0110h. The lower byte at address 0110h should receive #FFh and the upper byte at address 0111h should receive #00h as shown below:

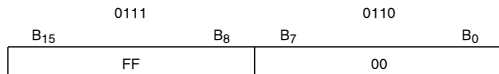


Configuration Register (Desired Result)

The most intuitive way to do this is:

```
LDD #00FFh
STD 0110h
```

but this will result in:

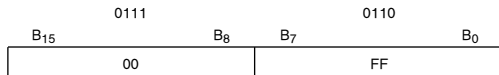


Configuration Register (Wrong Approach)

This routine is incorrect because the high-byte (#00h) is written to address 0110h instead of 0111h and the low-byte (#FFh) is written to address 0111h instead of 0110h. The reason for this is that the contents of ACCA are written first followed by those of ACCB. The correct way to do this is to swap the two bytes in the first instruction when writing the code.

```
LDD #FF00h
STD 0110h
```

resulting in:

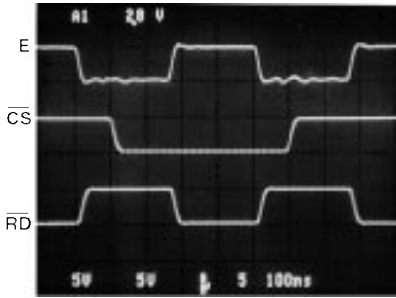


Configuration Register (Correct Approach)

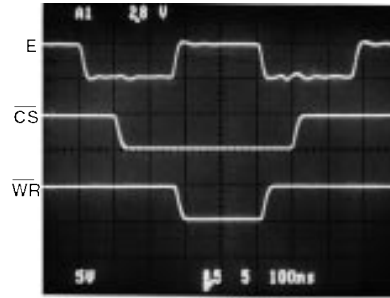
When using ACCD to write data to the DAS, make sure that the ACCD's upper-byte contains the data's lower-byte and its lower-byte contains the data's high-byte. Using ACCD to read from the FIFO and store data in memory results in having the upper and lower bytes of the converted data swapped. This does not cause any problems if the data from memory is interpreted correctly. However, if the user does not want to store the data in this swapped format, ACCD should not be used to write to memory. After the data has been read from the FIFO with the ACCD, accumulators A and B should be used to write the data to memory, not ACCD. Specifically, the data in ACCB should be written to the lower address in memory and the contents of ACCA to the higher address. Now when ACCD is used to read conversion results that are stored in memory, it will have the upper and lower bytes of the data in a more logical format.

4.2 Hardware Description of the Interface Circuitry

The DAS (U7) is seen by the 68HC11 (U1) (Refer to *Figure 4*) as an I/O device placed at a certain location in memory. The interface consists of standard address decoding circuitry using U2, U3, and U4 and demultiplexing of the R/W signal line with U5 and U6. U2 is an 8-bit latch that is used to demultiplex the lower address byte from the data byte by using the address strobe signal AS. U4 is an 8-bit comparator that compares the upper address byte to the 8-bit value preset by S1. The value set by S1 determines what upper address byte the DAS is placed at. In this example it is set to 01h. The output of U4 enables U3. U3 is a three bit decoder used to generate the chip select of the DAS. ICs U5 and U6 create the RD and WR signals to the DAS. Refer to *Figure 3* for the timing diagrams of a read and write cycle. Jumpers J1 and J2 connect the V_{ref+} and V_{ref-} of the DAS to an external source or the on-board 5V supply. Header HDR1 connects the analog inputs to the DAS. The filter capacitors used for VA+, VD+, V_{ref+}, V_{ref-}, and V_{refout} should be as close to their respective pins as possible. Refer to section 5.0 of the data sheet for power supply and ground considerations.



TL/H/12050-3



TL/H/12050-4

FIGURE 3. Timing Diagrams Showing the E Clock, \overline{CS} , \overline{RD} and \overline{WR} Signals

The signals in *Figure 3* were generated by executing the following program:

```

Loop   LDAA $0100   ;Reads the DAS
        STAA $0100  ;Writes to the DAS
        BRA  Loop

```

In order to access all the DAS registers, at least twenty seven consecutive memory locations are needed. In this particular example the DAS is placed at address locations 0100h to 011Fh. This address range allows all the DAS registers to be accessed, which are located at addresses 0100h to 011Bh. (Refer to the data sheet for specific addresses of registers.) By selecting the appropriate settings on the dip switch S1, the user can choose the upper address byte the DAS is placed at.

4.3 Description of the Software

In the first part of the program (*Figure 5*), the DAS is initialized to meet the specifications needed for the furnace example. After the DAS has been initialized and a full auto-calibration is completed, the DAS is reset and instruction execution is started by writing a logic one in the configuration's start bit. The 68HC11 waits for an interrupt. When an interrupt is generated by the DAS, program execution jumps to the interrupt service subroutine. The actions taken by the interrupt service routine are based on which interrupt bits are set in the Interrupt Status Register. The FIFO_FUL interrupt is the only interrupt that is fully serviced by this program. It is important to note that the Interrupt Status register should not be polled because every time \overline{CS} is pulled low all internal clock-dependent activities of the DAS stop, e.g. the A/D converter, sequencer and timer. Conditions that need to be serviced must be done on an interrupt basis.

When a FIFO full interrupt occurs, the DAS is programmed to empty the five conversions stored in the FIFO starting at the address pointed to by the conversion pointer CONV_POINT. The CONV_POINT holds the address of where data is to begin being stored in memory. In this example, the conversion pointer is initialized to point to ad-

dress 00h. After reading the five conversions stored in the FIFO and putting them in memory, program execution resumes at the main program following the WAI instruction. This 68HC11 instruction puts the μ C in an idle state and waits for an interrupt to occur, at which time program execution will jump to the interrupt service routine. Index register X counts the number of data bytes read from the FIFO and stored in memory. It is also used as an offset to the CONV_POINT to give the address of where the data byte read from the FIFO is to be stored. The value in X is compared against the value CONV_BYTES. When it is greater than CONV_BYTES, program execution is halted. If it is less than CONV_BYTES, the 68HC11 jumps back to the WAI instruction and waits for another FIFO full interrupt to occur. In this example CONV_BYTES is equal to sixty. Since the circuit that was used for this example contains no external memory, the on board microcontroller RAM was used. If external memory is needed the software and board can be easily modified. A memory component can be placed at a certain location in the memory map by using one of the seven available signals from the 74H138 to generate the chip select. The conversion pointer, CONV_POINT needs to be initialized with the beginning address of where converted data is to be stored in memory and CONV_BYTES needs to be set to twice the desired number of conversions. For example, if 8192 samples are to be taken and are to begin being stored at address 1000h, CONV_BYTES should be set to 16384 and CONV_POINT to 1000h.

The DAS_LIMIT interrupt subroutine is intended to service watchdog conditions. In this furnace example no provisions have been made to deal with a watchdog interrupt except that of acknowledging its occurrence and returning to the main program. The manner in which a watchdog condition is handled is system-dependent and must be user-defined. The purpose of the FUL_CAL subroutine is to indicate when the DAS has completed its full auto-calibration cycle. The only action taken in the FUL_CAL interrupt subroutine is a return to the main program.

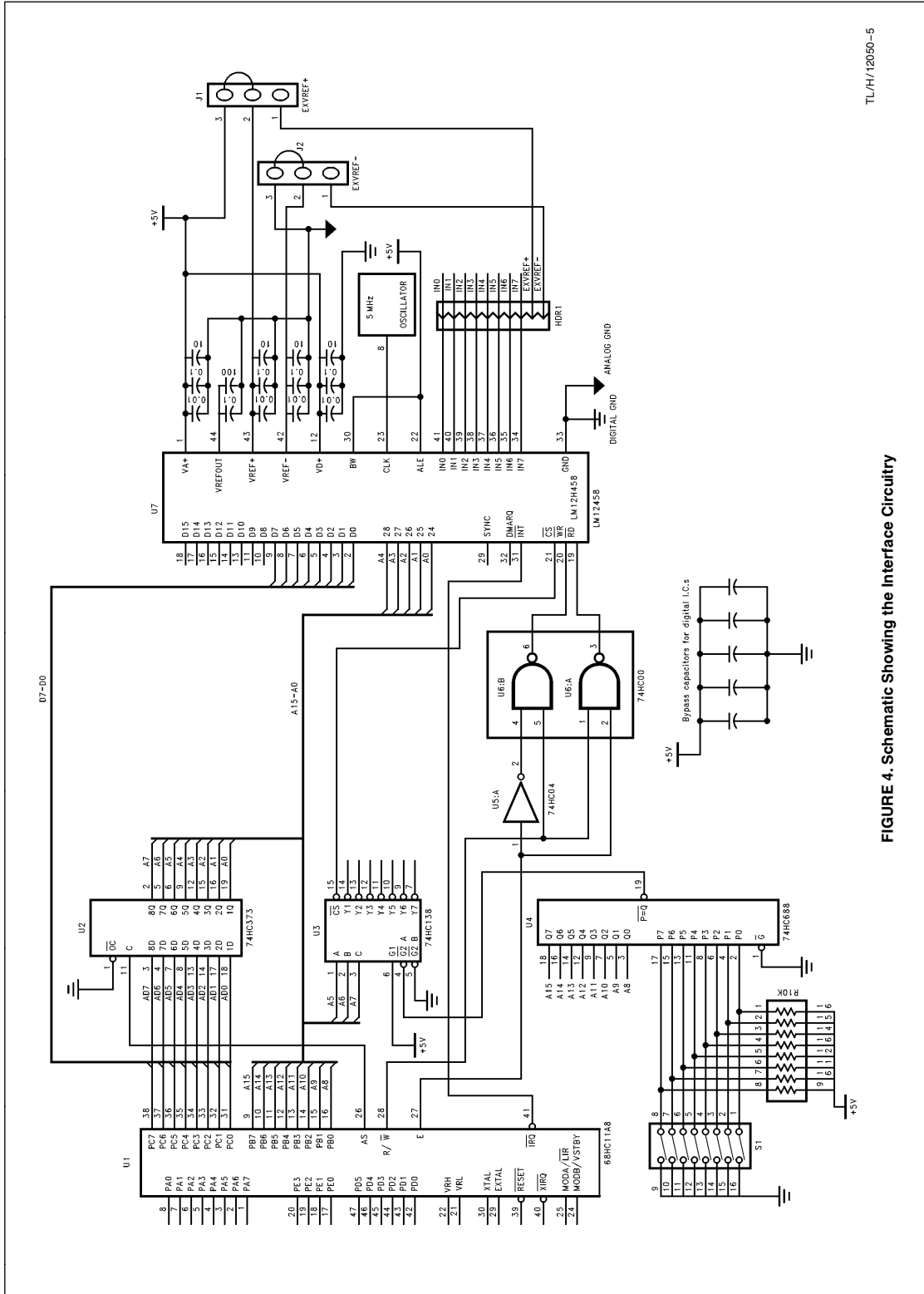


FIGURE 4. Schematic Showing the Interface Circuitry

```

INSTR0 EQU $0100
INSTR1 EQU $0102
INSTR2 EQU $0104
INSTR3 EQU $0106
INSTR4 EQU $0108
INSTR5 EQU $010A
INSTR6 EQU $010C
CONFIG EQU $0110
INT_EN EQU $0112
INT_STAT EQU $0114
TIMER EQU $0116
FIFO EQU $0118
LMT_STAT EQU $011A
FLOW_MAX EQU $0FFF
FLOW_MIN EQU $0000
PRES_MAX EQU $00FF
PRES_MIN EQU $1000
TIMER_SET EQU $2C0C
CONV_POINT EQU $0000
*
CONV_BYTES EQU $003C
STAT_HOLD EQU $00E0
FIFO_CNT EQU $1E
*
*****
;User defined limit.
;User defined limit.
;User defined limit.
;User defined limit.
;User defined. Conversions will begin being stored at
;this address.
;User defined. This example it is decimal 60.
*****
*
*****
ORG $E000
CLI Ummasks interrupt #IRQ.
*****
***** MAIN PROGRAM *****
LDY #$0000
LDX #$0000
STX CONV_POINT Memory location used to store contents of the interrupt status register.
*
* ***** Initialization of the DAS *****
* LDD #$0100 Resets the DAS AND SETS THE RAM POINTER TO 00
* STD CONFIG
*
* LDD #$0C2A Instruction 0 is used to set watchdog mode for
* STD INSTR0 the gas flow measurement with an acquisition delay time set.
*

```

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FIGURE 5. 68HC11 Assembly Program Listing

*	LDD #1008 STD INSTR1	Instruction 1 used to set watchdog mode for pressure measurements.
*	LDD #0000 STD INSTR2	Initializes instruction 2 in the INSTRUCTION RAM to measure T1 single-ended in 12-bit + sign mode.
*	LDD #2000 STD INSTR3	Instruction 3 measures T1-T2 in 12-bit + sign mode T2 is at IN1.
*	LDD #4000 STD INSTR4	Instruction 4 measures T1-T3 in 8-bit mode. T3 is at IN2
*	LDD #6024 STD INSTR5	Instruction 5 measures gas flow in 8-bit mode at IN3 with an acquisition delay time set (D=2).
*	LDD #1104 STD INSTR6	Instruction 6 measures pressure in 8-bit mode at IN4.
*	LDD #0001 STD CONFIG	Sets the RAM Pointer to 01.
*	LDD #FLOW_MAX STD INSTR0	Sets the watchdog upper limit for maximum flow. Limit #1.
*	LDD #PRES_MAX STD INSTR1	Sets the watchdog upper limit for maximum pressure. Limit #1.
*	LDD #0002 STD CONFIG	Sets the RAM Pointer to 10.
*	LDD #FLOW_MIN STD INSTR0	Sets the lower watchdog flow limit.
*	LDD #PRES_MIN STD INSTR1	Sets the lower watchdog pressure limit.
*	LDD #TIMER_SET STD TIMER	Configures the timer to a preset value so that a 50Hz throughput rate is achieved.
*	LDD #1328 STD INT_EN	Enabling FIFO full (=5 CONV.), watchdog and auto-cal interrupts.
*		

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FIGURE 5. 68HC11 Assembly Program Listing (Continued)

```

*          LDD INT_STAT      Reads interrupt status register to clear it.
*
*          LDD #0800        Starts a full auto-calibration cycle.
*          STD CONFIG      An interrupt will be generated when done.
*
*          WAI              Waits for interrupt to occur. When an interrupt is generated
*                          program control resumes at the interrupt service routine.
*
*          ***** STARTS CONVERSION *****
*          LDD #0200        Resets the DAS
*          STD CONFIG
*
*          CLI              Enables 68HC11 interrupt.
*          LDD #8100        Starts conversion with sync out.
*          STD CONFIG
*
*          WAI              Waits for interrupt to occur. When an interrupt is generated
*                          program control resumes at the interrupt service routine.
*
*          CPX #CONV_BYTES  Compares number of conversion bytes (value stored in register X)
*          BLT CONV        to decimal number 60. Two bytes per conversion.
*          STOP            Program execution is halted.
*
*          ***** END OF MAIN PROGRAM *****
*          ***** INTERRUPT SERVICE ROUTINE *****
*
*          LDAA INT_STAT    Reads the lower byte of the interrupt status register
*          STAA STAT_HOLD  and stores the result at address STAT_HOLD.
*
*          LDAA STAT_HOLD
*          ANDA #04
*          BGT FIFO_FUL    Checks bit 2 to determine if FIFO full was
*                          the source of the interrupt. If so, continue at FIFO_FUL subroutine.
*
*          LDAA STAT_HOLD
*          ANDA #01
*          BGT DAS_LIMIT   Checks bit 0 to determine if watchdog limit was the
*                          source of the interrupt. If so, resume program at
*                          DAS_LIMIT subroutine.

```

FIGURE 5. 68HC11 Assembly Program Listing (Continued)

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